

## CALL FOR PAPERS

# Special Issue of the IEEE Transactions on Dielectrics and Electrical Insulation Electrets and Related Phenomena

We are pleased to announce that the **June 2018** issue of the IEEE Transactions on Dielectrics and Electrical Insulation (TDEI) will be a special issue on electrets and related phenomena. This issue is open to **all** authors. Presenters of papers at the IEEE 16<sup>th</sup> International Symposium on Electrets (ISE16) to be held during September 4-7, 2017 in Leuven (Belgium) are especially encouraged to submit their work to this special issue. For more information on ISE16 please go to [www.ise16.eu](http://www.ise16.eu).

Topics include, but are not limited to:

- Charge related phenomena in dielectrics (injection, storage, transport, trapping, measurements)
- Dielectric and space charge relaxations in polymers and organics
- Dielectric and electrical responses of dielectrics to high electric fields
- Dielectric relaxation spectroscopy
- Energy storage in dielectrics and ionic materials
- Thermally stimulated phenomena
- Electrets for energy harvesting: principle, design, characterization and applications
- Piezo-, pyro- and ferroelectrets
- Electrocaloric and pyroelectric materials
- Piezo-electric phenomena in polymers and organics/biomaterials
- Applications of organic and polymer based piezo-electric materials
- Electrets and functional polymers in organic electronics
- Optical effects, photoelectrets
- Electrostatic and dielectric phenomena in life sciences - bioelectrets
- Soft transducers: sensors and actuators, including dielectric elastomers
- Nanoscale electrostatic, dielectric and electret materials
- Electret and dielectric phenomena in nanoscale structures

Authors are invited to submit their papers to the Guest Editors of the Special Issue no later than **September 15, 2017**, at the TDEI website (<http://www.cloznet.com/ieeetdei>). On the submission form there is a location for Special Issue paper submission where the name of the Guest Editor can be chosen. Instructions for the preparation of manuscripts and a template are available at the website or directly from: <http://www.cloznet.com/ieeetdei/TDEI%20Template.doc>

In accordance with IEEE policy, papers that have been published in any conference proceedings cannot be republished. A plagiarism tool will be used to verify originality. Therefore, authors of the ISE16 proceedings are strongly advised to significantly expand and enhance their conference paper versions prior to submission to this Special Issue of the IEEE TDEI.

Further questions concerning this Special Issue could be directed to either one of the two Guest Editors or directly to the Editor-in-Chief of the IEEE Transaction on Dielectrics and Electrical Insulation Professor Reuben Hackam ([hackam@uwindsor.ca](mailto:hackam@uwindsor.ca)). The Guest Editors for this special issue are:

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